

ICICM2019

The 4th International Conference on
Integrated Circuits and Microsystems

October 25-27, 2019 | Beijing, China

Submission Deadline: August 30, 2019



TOPICS

Thz and Microwave MicroSystem
Devices and Circuits for Wireless System
Application Specific Circuits and Systems for Communication
Digital, Analog, Mixed Signal IC and SOC design technology
Silicon integrated circuits and manufacturing
Low-power, RF devices & circuits
IC Computer-Aided –Design technology, DFM
Silicon/germanium devices and device physics
Interconnect, Low K, High K and other process technologies
Unconventional and nano-electronics
Organic semiconductor devices and technologies
Compound semiconductor devices and circuits
Displays, sensors and MEMS
Semiconductor materials and material characterization
Packaging and testing technology
Solar cell & other devices for new energy sources
Modeling and simulation
Equipment technology
Reliability
Displays, sensors and MEMS
Advance memories technology (Flash, FeRAM, PCM, ReRAM, MRAM etc.)

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INTRODUCTION

ICICM-International Conference on Integrated Circuits and Microsystems is an annual conference, which was co-sponsored by IEEE, University of Electronic Science and Technology of China and Southeast University, China, and technically assisted by many organizations worldwide. The aim of ICICM is to provide a platform for researchers, engineers, academicians as well as industrial professionals from all over the world to present their research results and development activities in Integrated Circuits and Microsystems.

The previous 3 editions ICICM were successfully held in Chengdu on Nov.23-25, 2016, in Nanjing during Nov.8-11, 2017 and in Shanghai from Nov.24 to 26, 2018. This year, we are proud to announce the 4th International Conference on Integrated Circuits and Microsystems to be held on October 25-27, 2019 in Beijing, China.

PROCEEDINGS

All accepted papers after proper presentation and registration will be collected in the conference proceedings, which will be submitted and reviewed in the **IEEE Xplore**, **Ei Compendex**, **Scopus**, and **CPCI (Web of Science)** after the conference

SPEAKERS

★Keynote Speakers★

Prof. Ljiljana Trajkovic, IEEE Fellow, Simon Fraser University, Canada

Prof. Fei Yuan, Ryerson University, Canada

Prof. Zou Zhuo, Fudan University, China

★Invited Speakers★

Prof. Sheng-Lyang Jang, National Taiwan University of Science and Technology, Taiwan

Prof. Dai Yong-Sheng, Nanjing University of Science & Technology, China

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